

# Defect annealing in 4H-SiC

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# Characterization Techniques

## Detection and characterization of electrically active defects:

- *Deep Level Transient Spectroscopy*: concentration, energy level (enthalpy) and capture cross section of electrically active defects.
- *Capacitance-Voltage Characterization*: free charge carrier distribution.
- *Electron Beam Induced Current*: spatial distribution and recombination strength of extended defects.

## Characterization of the device:

- *Current-Voltage Characterization*: behavior of dark current in presence of defects.
- *Charge Collection Efficiency*: effect of the defects on sample performance as a charged particle detector.

# Applications

- Defective State analyses to predict trapping effects.
- Spatial distribution of major recombining centers.
- Annealing and recovery of free charge carriers at low temperature.
- Irradiation effects (radiation hardness).
- Analysis of irradiation-induced compensation effects.
- CCE analysis as a function of irradiation and annealing temperature.



# Material

- **n 4H-SiC** epilayer grown by CVD:  
 $N_D = 2.2 \times 10^{15} \text{ cm}^{-3}$ ,  $30 \mu\text{m}$  thick
- Au Schottky contact,  $\phi = 2 \text{ mm}$ ,  $1000 \text{ \AA}$  thick

**IRRADIATION:**  
**8.6 MeV**  
**electrons at**  
**different**  
**doses/fluences**

circular Schottky contact  
*Au* ( $1000 \text{ \AA}$ ),  $\Phi = 2 \text{ mm}$

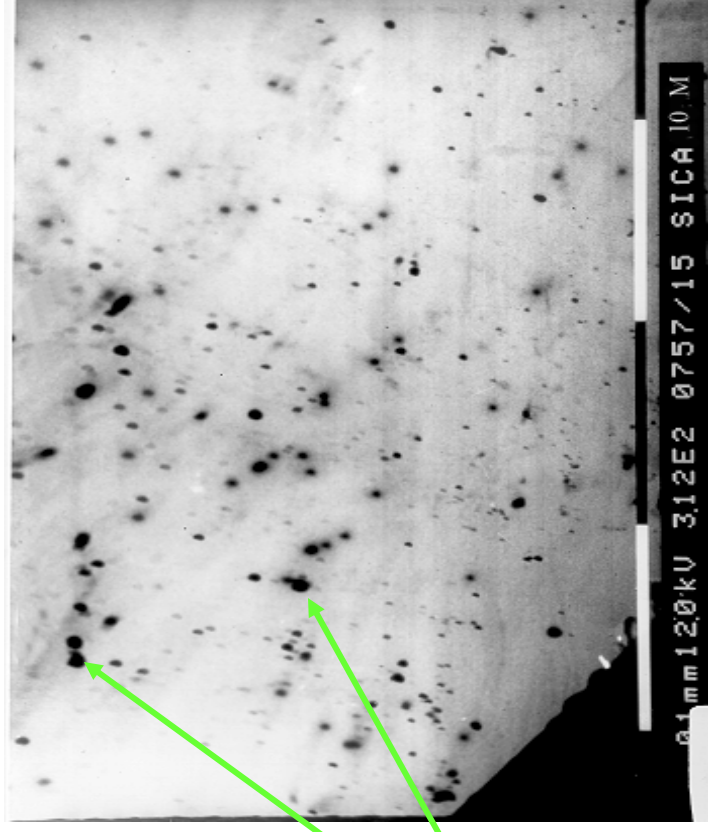
Si-face

n, 4H – SiC, $30 \mu\text{m}$ $N_D = 2.2 \cdot 10^{15} \text{ cm}^{-3}$	Si-face
$n^+$ , buffer, $1 \mu\text{m}$ , $N_D = 10^{18} \text{ cm}^{-3}$	
$n^+$ , 4H – SiC, $360 \mu\text{m}$ <i>substrate</i> $N_D \cong 7 \cdot 10^{18} \text{ cm}^{-3}$ 10 micropipe/cm <sup>2</sup>	

Ohmic contact - *Ti/Pt/Au* C-face

Dose	Fluence ( $\text{cm}^{-2}$ )
2 Mrad	$4.74 \times 10^{13}$
10 Mrad	$2.37 \times 10^{14}$
40 Mrad	$9.48 \times 10^{14}$

## EBIC micrographs

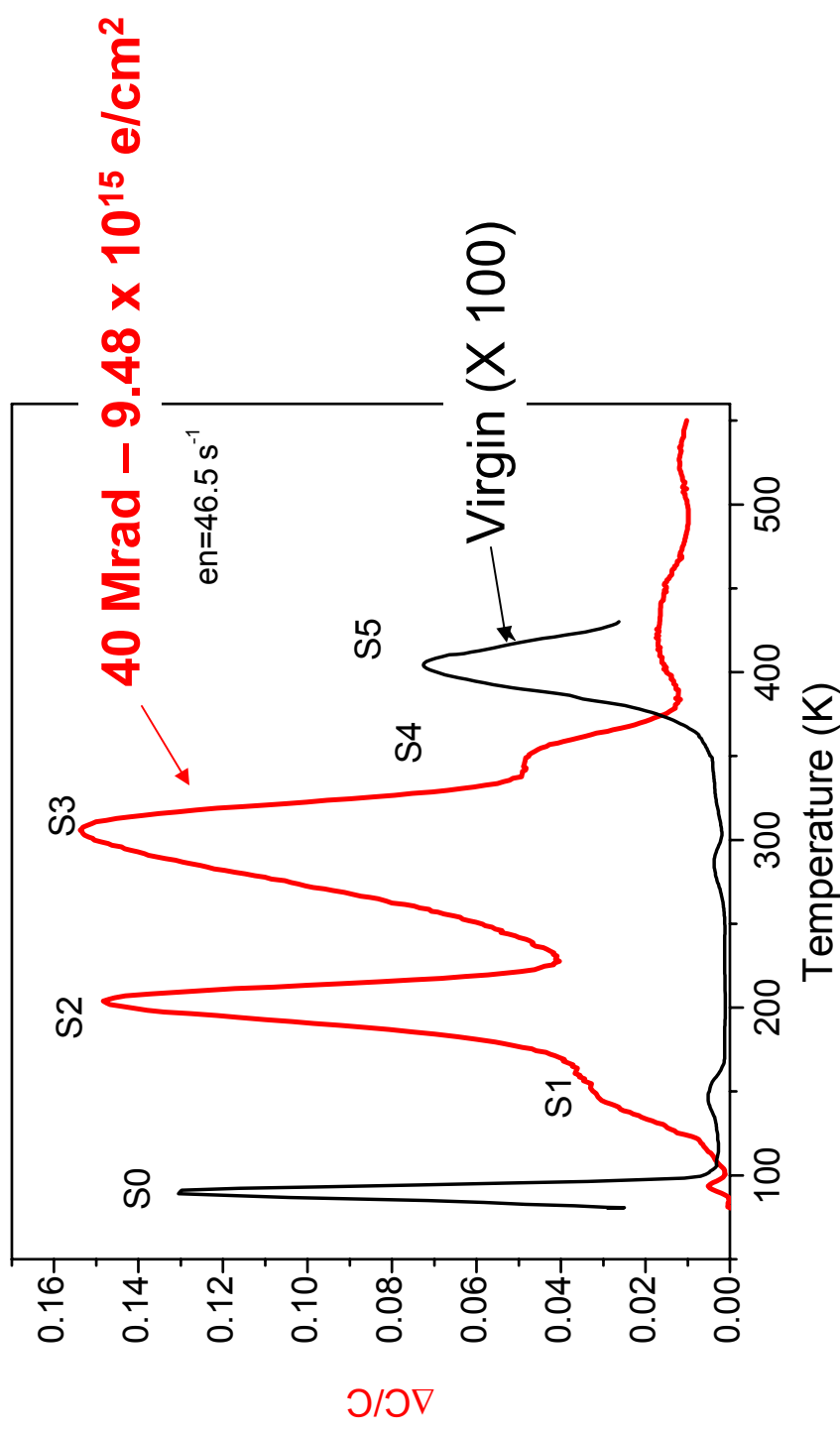


Dislocations  
appear as  
dark spots on  
the surface

Dislocation  
density is  
about  
 **$10^5 \text{ cm}^{-2}$**

EBIC contrast  
up to 40%

# DLTS analysis – Irradiation induced deep levels

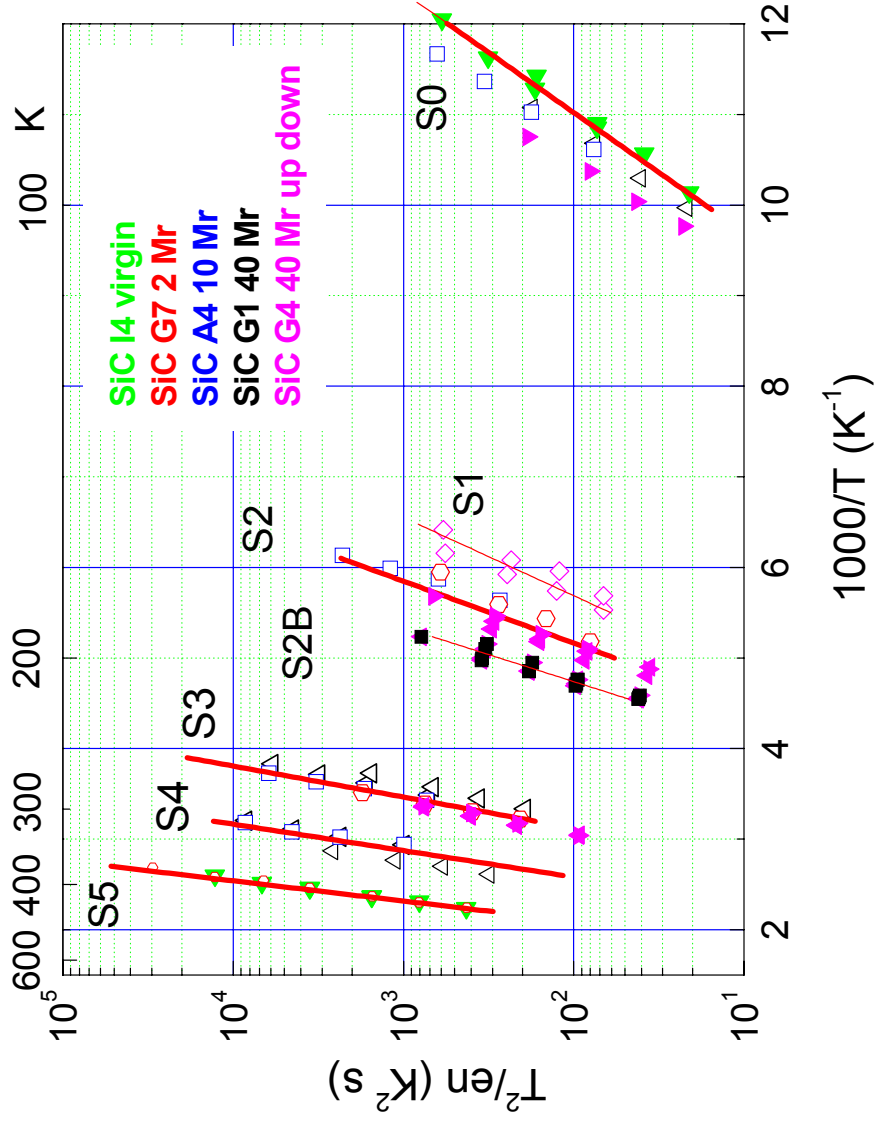


# DLTS analysis – Trap parameters

Trap level	Deep level enthalpy $E_T$ (eV)	Concentration $N_T$ (cm <sup>-3</sup> )	Capture cross section $\sigma_{inter}$ (cm <sup>2</sup> )	Introduction rate $\eta$ (cm <sup>-1</sup> )
<b>S0</b>	$E_C - 0.15$	$1.4 \times 10^{13}$	$6.0 \times 10^{-16}$	0.02
<b>S1</b>	$E_C - 0.23$	$5.5 \times 10^{13}$	$9.3 \times 10^{-16}$	0.116
<b>S2</b>	$E_C - 0.39$	$4.0 \times 10^{14}$	$1.7 \times 10^{-15}$	0.84
<b>S3*</b>	$E_C - 0.50 / 0.65$	$4.2 - 5.4 \times 10^{14}$	$1.4 \times 10^{-16}$ $1.7 \times 10^{-14}$	0.88
<b>S4</b>	$E_C - 0.75$	$1.3 \times 10^{14}$	$6.6 \times 10^{-15}$	0.27
<b>S5</b>	$E_C - 0.89$	$4.6 \times 10^{13}$	$7.2 \times 10^{-15}$	0.09

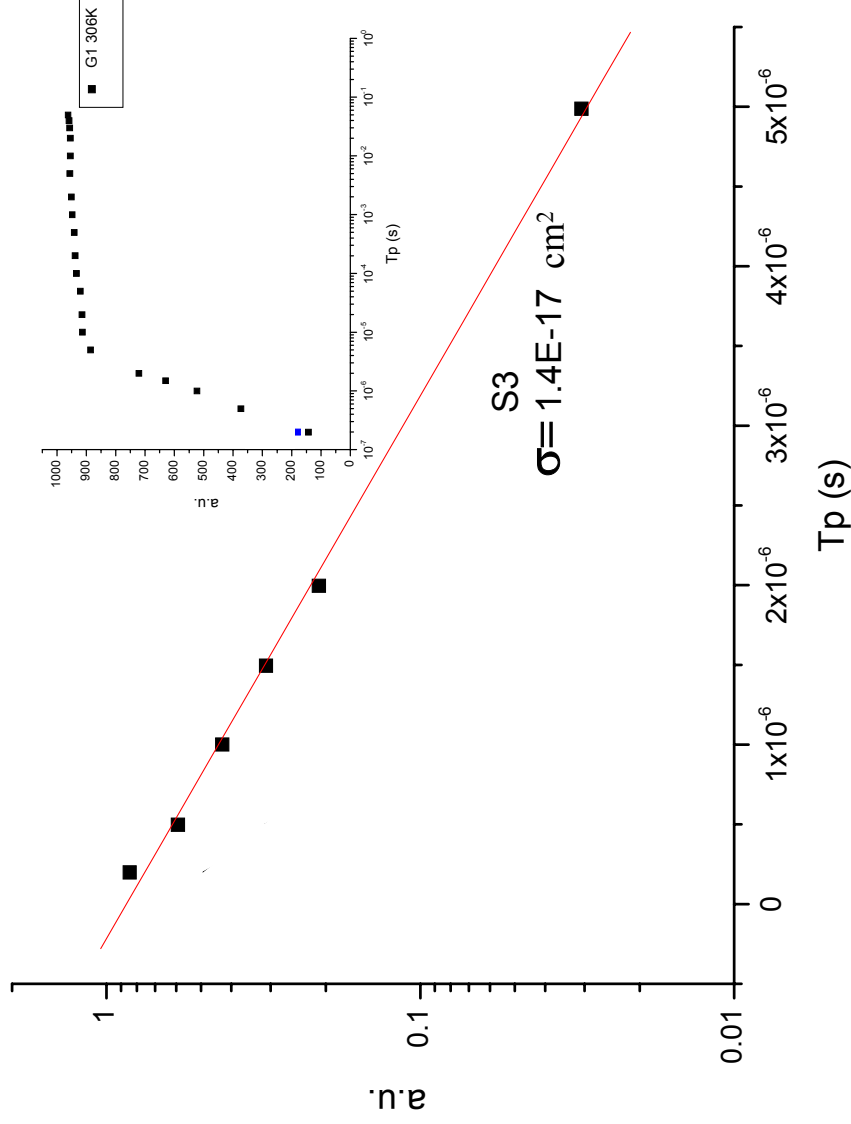
\* S3 undergoes annealing at T~400-470K; the parameters after annealing are typical of the level known from the literature as Z1/Z2

# DLTS analysis – Arrhenius Plot





# DLTS analysis – Filling Kinetics



# DLTS and annealing analysis

1. Run 80-360K

2. Run 80-400K

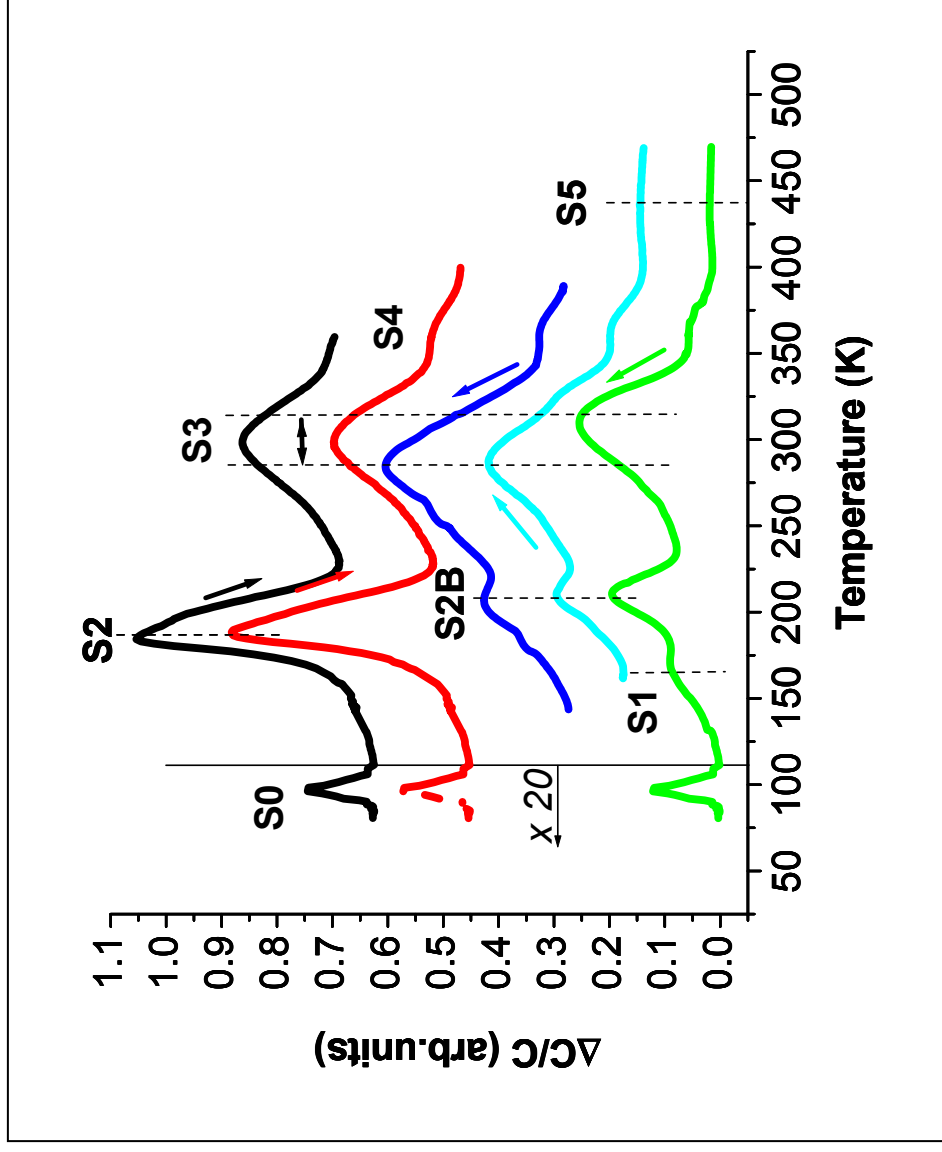
3. Run 400-150K

4. Run 160-470K

5. Run 470-80K

1<sup>st</sup> annealing stage  
(360 – 400 K):

- very strong decrease of peak S2
- slight amplitude gain and temperature shift of S3
- S2B and S1 become resolved

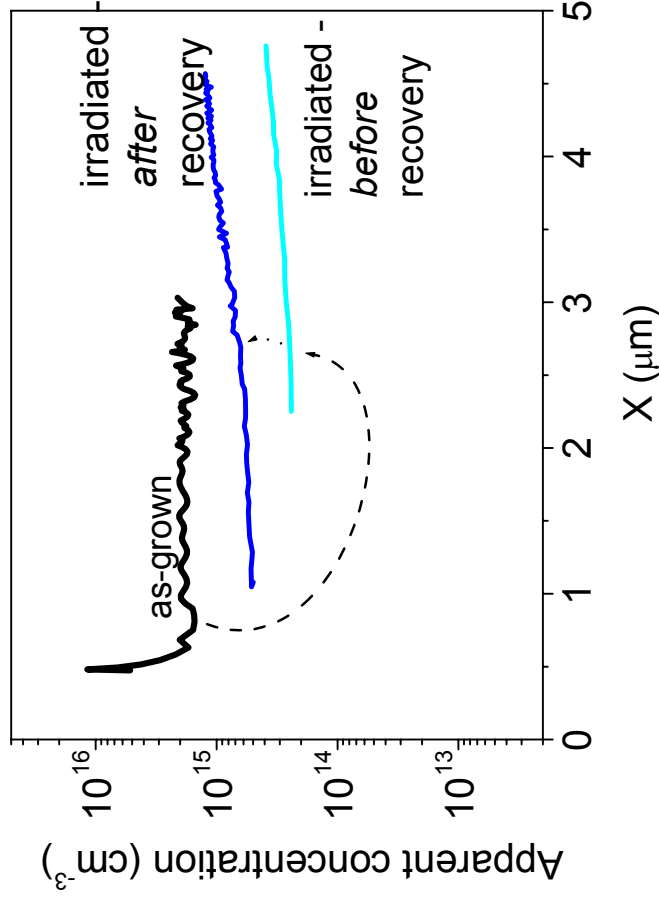


2<sup>nd</sup> annealing stage  
(400 – 470 K):

- blue shift of S3 activation energy
- sharpening of S3 peak

## C-V analysis

- **Strong compensation** of free charge for  $\Phi = 9.48 \times 10^{14} \text{ cm}^{-2}$  ( $\sim 1/10$  of the as-grown value).
- **Significant free charge density increase after annealing of peak S2** at 360K-400K.



Post-recovery free charge increase



✓ Possible explanation:  
recombination and annihilation  
of the defect related to level S2

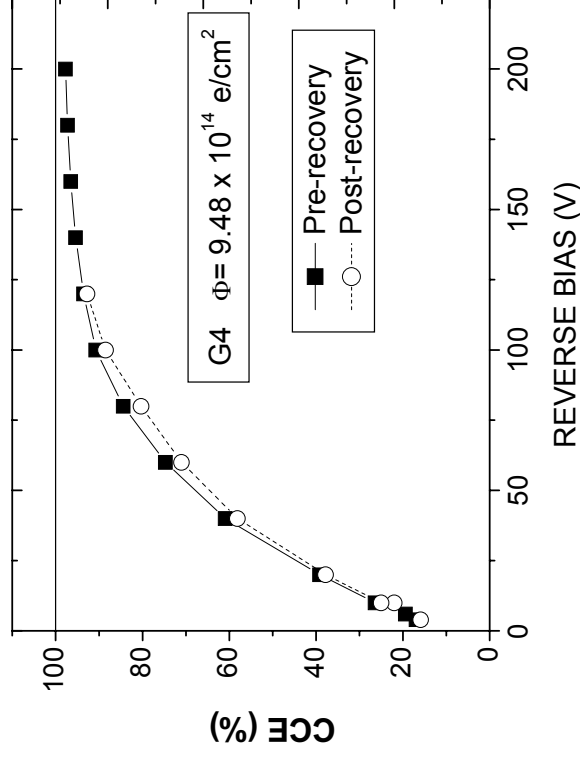
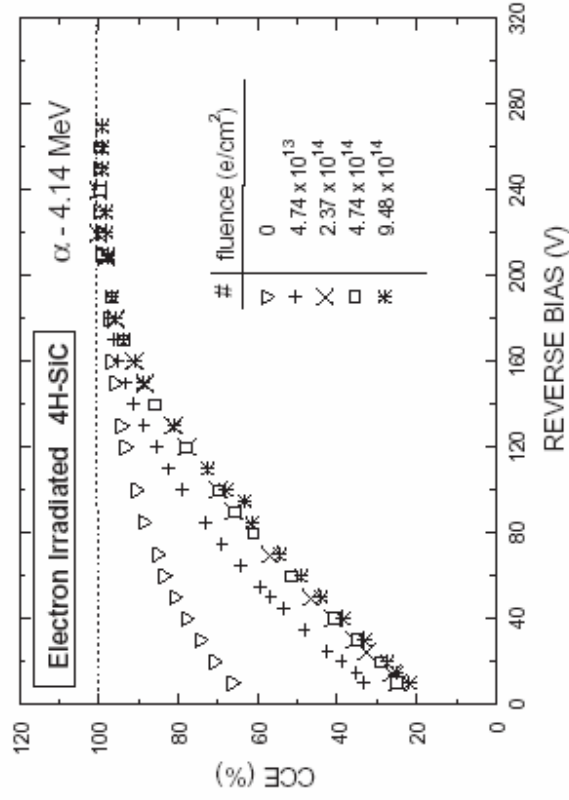
# CCE characterization

## CCE vs. irradiation dose

- In the diffusion regime (Bias < ~160V) CCE is degraded by the introduction of traps.
- In the drift regime (Bias > ~160V) CCE saturates to 100% for all irradiation doses.

## CCE vs. annealing

- Low T annealing does not change the CCE of the detector.

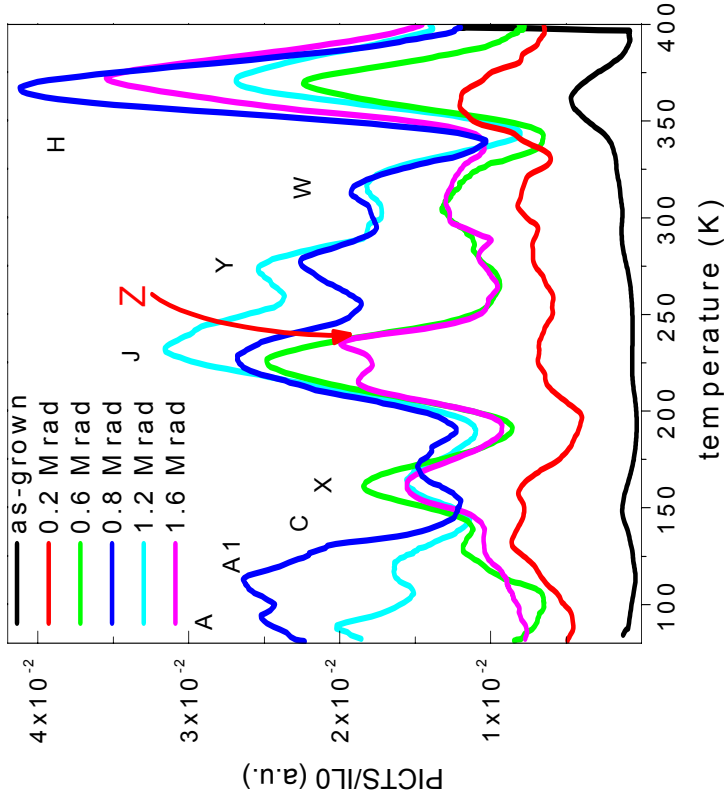


## Conclusions

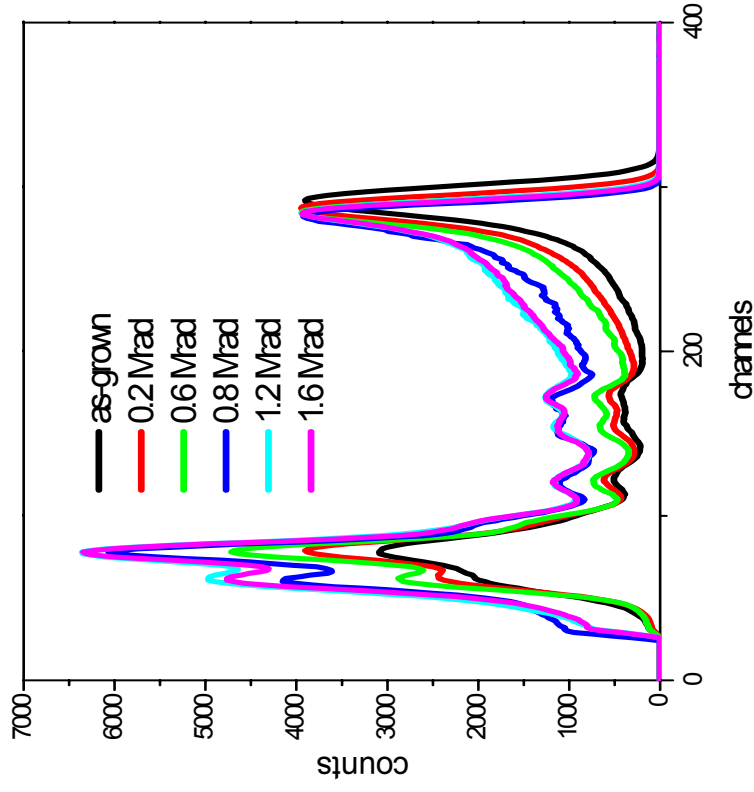
- Electron irradiation
  - Introduction of at least 4 trap levels.
  - Strong compensation of free carrier density.
- 1<sup>st</sup> Annealing stage (360K-400K):
  - Disappearance of level S2 ( $E_c-0.39$  eV).
  - Free carrier density increase (recovery).
  - Rearrangement of peak S3.
- 2<sup>nd</sup> Annealing stage (400K-470K):
  - Blue shift of S3 level energy; S3 parameters are those of Z1/Z2 level.
- Possible recovery cause: annihilation of the defect related to S2 during 1<sup>st</sup> annealing stage (360K-400K).
- Detector performance preserved up to  $\Phi \sim 10^{15}$  cm<sup>-2</sup>.
  - CCE saturates to 100% in drift regime and remains unchanged upon annealing.

# 9 MeV electron irradiation on CdZnTe

## PICTS

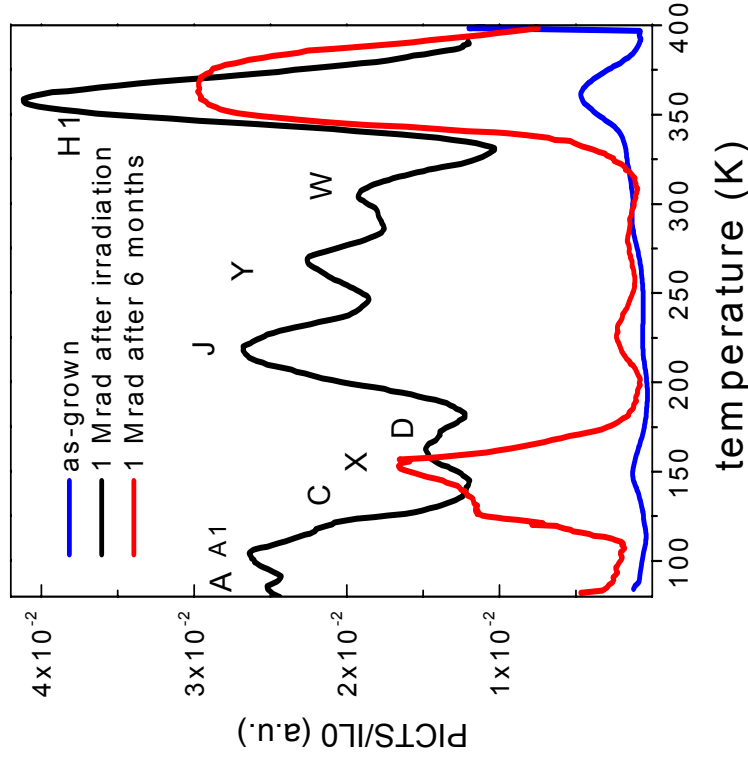


## Gamma Spectroscopy



# Time recovery of 9 MeV electron irradiated CdZnTe (6 months)

## PICTS



## Gamma Spectroscopy

